Product Change Notification - KSRA-22MRJA026

Date: 04 Dec 2017

Product Category: Temperature Sensors

Notification subject: CCB 3174 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 8L TDFN (2x3x0.8mm) package at NSEB assembly site

Notification text:

PCN Status:
Initial notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 8L TDFN (2x3x0.8mm) package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T die attach, and G770HCD molding compound material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, and G700LTD molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)	UTAC Thai Limited LTD. (NSEB)
Wire material	Au Wire	CuPdAu Wire
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, and G700LTD molding compound material at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2017					**-->**	**April 2018**				
Workweek	44	45	46	47	48		14	15	16	17	18
Initial PCN Issue Date					X						
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
November 29, 2017: Issued initial notification.
December 04, 2017: Re-Issued initial PCN to correct the attachment.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-22MRJA026_Affected CPN.pdf
PCN_KSRA-22MRJA026_Qual Plan.pdf
PCN_KSRA-22MRJA026_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-22MRJA026
CATALOG_PART_NBR
MCP98244T-BE/MNY
MCP98244T-BE/MNYAA
MCP98244T-BE/MNYAB
MCP9844T-BE/MNY
MCP9844T-BE/MNYAA
MCP9844T-BE/MNYAB
MCP98244T-BE/MNYAC